



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Donald Craig Foster, Kelly Robbins McKendrick, Sr.
Assignee: Amkor Technology, Inc.
Title: Leadframe Having Fine Pitch Bond Fingers Formed Using Laser Cutting Method
Serial No.: 09/895,501 Filing Date: June 29, 2001
Examiner: David E. Graybill Group Art Unit: 2827
Docket No.: M-11315 US

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COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION MAILED OCTOBER 4, 2002

Dear Sir:

This communication is responsive to the Office Action mailed October 4, 2002 for the above-referenced application. Applicants respectfully request that the Examiner allow the application in view of the amendments and remarks set forth below.

IN THE CLAIMS

Claims 1, 16 and 25-41 are cancelled. New claims 42-67 are added. Below is a listing of the now-pending claims.

17. A method of making a semiconductor package, the method comprising:
providing a leadframe including a plurality of leads within and connected to a frame,
wherein at least an inner end portion of each lead is singulated by laser cutting;
mounting a chip on the leadframe;
electrically coupling the chip to the inner end portion of a plurality of the leads; and
encapsulating the chip and the inner end portion of the leads.

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